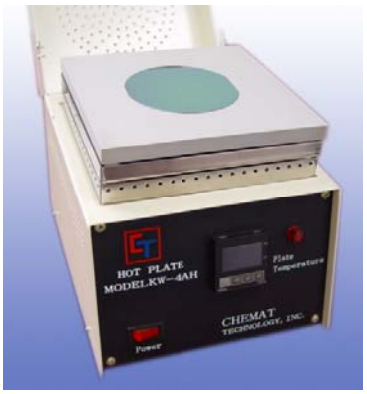
KW-4AH Compact Hotplate

Utilization of hotplates to cure the films have several advantages over conventional type ovens: (1) decrease bake time; (2) increase reproducibility and (3) better film quality. The KW-4AH compact hotplate has uniform temperature profile across the substrate to provide even heating the films and coatings. No skin effect occurs on the hotplate since the hotplate baking heats the substrate from the bottom up. This "inside out" mechanism is especially for baking thick films since solvents in the films nearest the substrate are baked off before the film surface seals over. The KW-4AH hotplate increases throughput from a faster warmup of the substrate. Bake times will be measured in seconds, rather then minutes or hours, as in conventional ovens.





The KW-4A hotplate is a compact and easy-to-use hotplate for baking and curing thin films and coatings. Its rugged, portable design, and temperature uniformity make it a versatile tool for all types of research facilities. In conjunction with the KW-4A spin-coater, the system can be used to fabricate metal oxide thin films, polymer coatings and metal organic thin films.



Specifications

Operation:	Manual Load
Process Control:	Program
Temperature Resolution:	1°C
Temperature Range:	50—350°C
Substrate Size:	6 inch

Options

- 600°C Maximum Temperature
- 0.1°C Resolution

Temperature Profile

